



Material Content Data Sheet



Sales Product Name		IPS090N03L G		Issued		31. July 2018		
MA#		MA000788536						
Package		PG-TO251-3-311		Weight*		333.81 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.720	0.22	0.22	2158	2158
leadframe	inorganic material	phosphorus	7723-14-0	0.047	0.01		140	
	non noble metal	iron	7439-89-6	0.156	0.05		466	
	non noble metal	copper	7440-50-8	155.372	46.53	46.59	465452	466058
	non noble metal	aluminium	7429-90-5	0.930	0.28	0.28	2787	2787
wire	non noble metal	aluminium	7429-90-5	0.930	0.28	0.28	2787	2787
encapsulation	organic material	carbon black	1333-86-4	0.331	0.10		991	
	plastics	epoxy resin	-	19.968	5.98		59820	
	inorganic material	silicondioxide	60676-86-0	130.065	38.96	45.04	389638	450449
leadfinish	non noble metal	tin	7440-31-5	3.002	0.90	0.90	8992	8992
plating	inorganic material	phosphorus	7723-14-0	0.004	0.00		11	
	non noble metal	nickel	7440-02-0	1.555	0.47	0.47	4657	4668
solder	non noble metal	tin	7440-31-5	0.020	0.01		61	
	noble metal	silver	7440-22-4	0.025	0.01		76	
	non noble metal	lead	7439-92-1	0.971	0.29	0.31	2907	3044
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		19	
	non noble metal	iron	7439-89-6	0.021	0.01		62	
	non noble metal	copper	7440-50-8	20.617	6.18	6.19	61763	61844
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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